

## Bill of Materials

## TI DESIGNS

## TIDA-00532

ltem	Qty	Reference	Part Description	Manufacturer	Manufacturer
1	4	ANT 5G ANT 24G TX 5G TX	Connector, End launch SMA, 50 ohm, SMT	Cinch Connectivity Solu	Part Number 142-0701-851
2		C1, C12, C23	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0402	TDK	C1005C0G1H331J
3	_	C2, C22	CAP, CERM, 0.1uF, 10V, +/-10%, X5R, 0201	Samsung	CL03A104KP3NNNC
4	_	C3, C21	56pF, 0201	Murata	GRM0335C1H560JA01D
5	2	C4, C15	CAP, CERM, 1000pF, 16V, +/-10%, X7R, 0201	Murata	GRM033R71C102KA01D
6	2	C5, C8	CAP, CERM, 2.2uF, 10V, +/-20%, X5R, 0201	Samsung	CL05A225KQ5NNNC
7	4	C6, C9, C10, C13	CAP, CERM, 0.1uF, 6.3V, +/-10%, X5R, 0402	TDK	C1005X5R0J104K
8	2	C7, C16	CAP, CERM, 10 μF, 10 V, +/- 20%, X5R, 0402	Samsung	CL05A106MP5NUNC
9	1	C14	CAP CER 12PF 25V 5% NP0 0201	Murata	GRM0335C1E120JA01D
10	1	C17	CAP, TA, 100uF, 16V, +/-10%, 0.1 ohm, SMD	Kemet	T495X107K016ATE100
11	1	C18	CAP, CERM, 4.7 μF, 10 V, +/- 20%, X5R, 0402	Samsung	CL05A475MP5NRNC
12	1	C27	CAP CER 3PF 25V NP0 0201	Murata	GRM0335C1E3R0CA01D
13	1	C38	CAP CER 22PF 50V 5% NP0 0201	Murata	GRM0335C1H220JA01D
14	1	J5	Standard Banana Jack, Insulated, Red	Keystone	6091
15	1	J7	Standard Banana Jack, Insulated, Black	Keystone	6092
16	-		Inductor, 470nH, 2.4A, 0.04 ohm, SMD	Murata	LQM21PNR47MGH
		LNAEN_5G, LNAEN_24G, PAEN_5G, PAEN_24G, PA_VDC, 81EN, VSEL,			
17			Header, 3-Pin		HTSW-103-07-G-S
18	-		RES, 0 ohm, 5%, 0.063W, 0402	Vishay Dale	CRCW04020000Z0ED
19	-	,	RES, 0 ohm, 5%, 0201	Panasonic	ERJ-1GN0R00C
20	1	U1	3.3V, 1.2A, 6MHz, Miniature Step-Down DC-DC Converter	Texas Instruments	LM3281

Item	Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number
21	1	U2	2.4GHz, 801.11n PA	Triquint	TQF9046
22	1	U3	5GHz, 802.11ac PA	Triquint	TQP887051

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